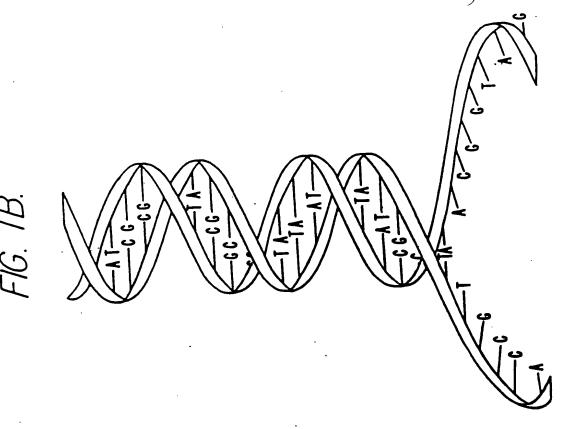
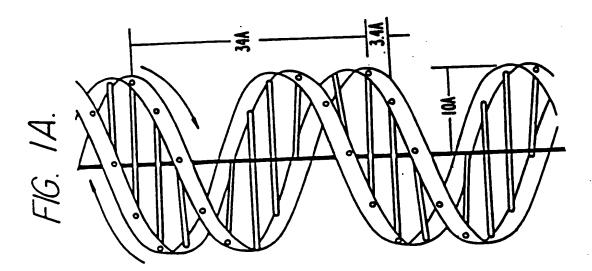
Title Affinity Based Self-Assembly Systems and Devices for Photonic and Electronic Applications INVENTOR(S): Heller
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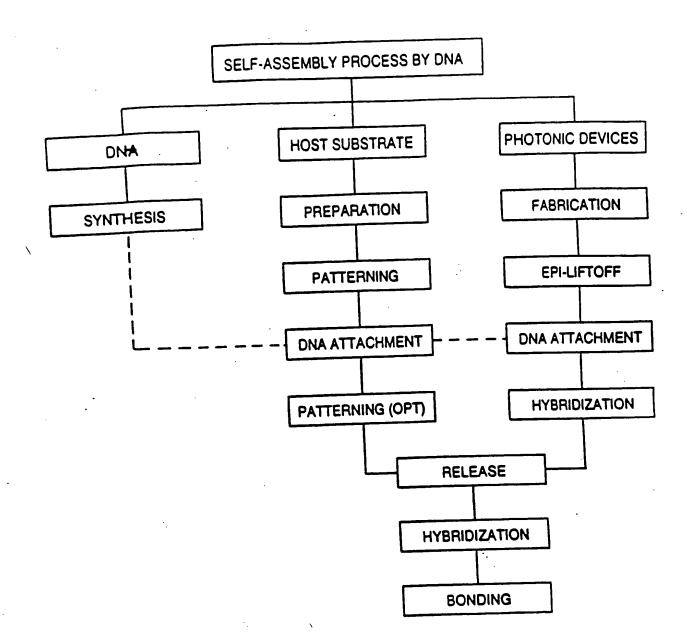
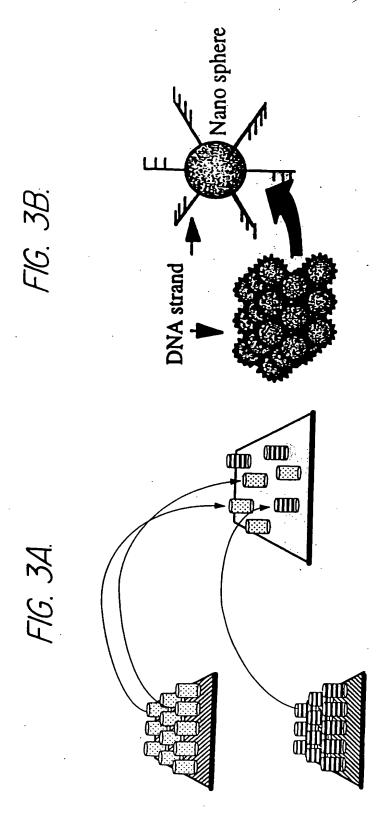


FIG. 2.

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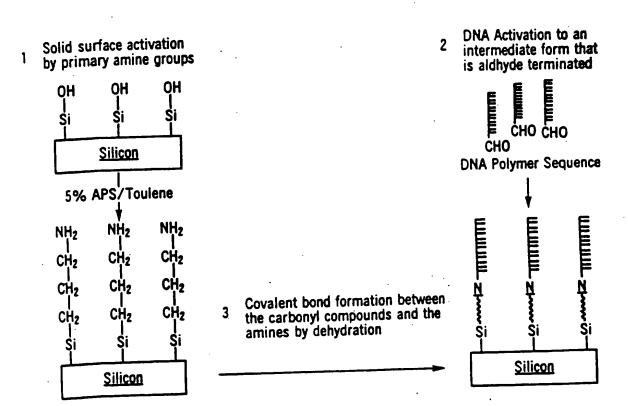


FIG. 4.

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7. DNA Attachment

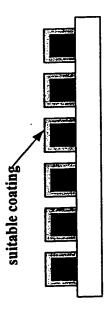


for quasi-Brownian motion capability 2. Suitable coating of device surface

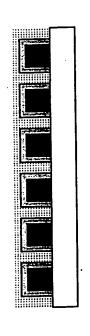
1. Standard micro/nano device fab. with

sacrificial layer for liftoff

6. Metalization

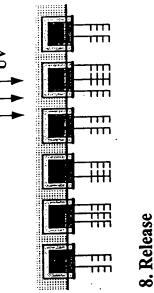


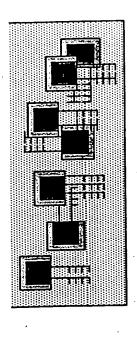
3. Support with polyimide or black wax



4. Epi-liftoff







Spridization with complement

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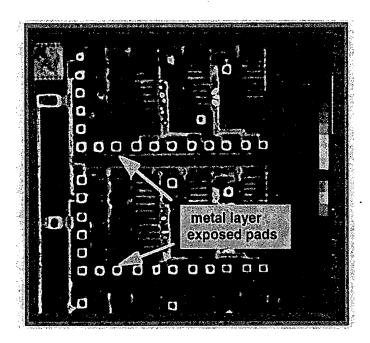


Fig. 6

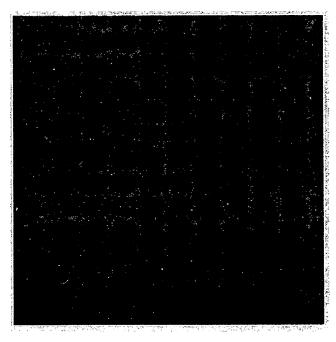


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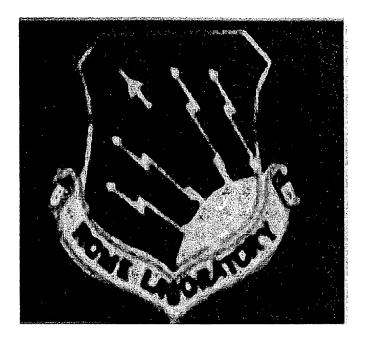


Fig. 8A

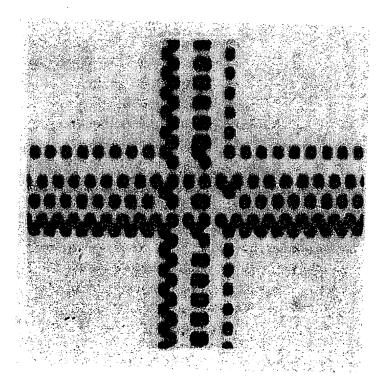


Fig. 8B

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FIG. 9

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL

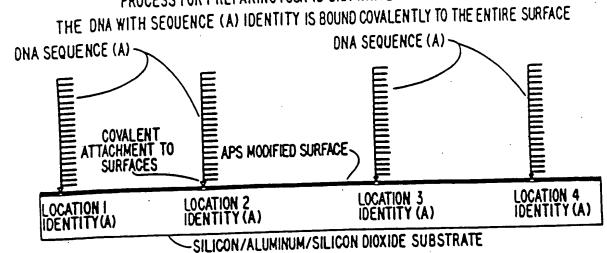
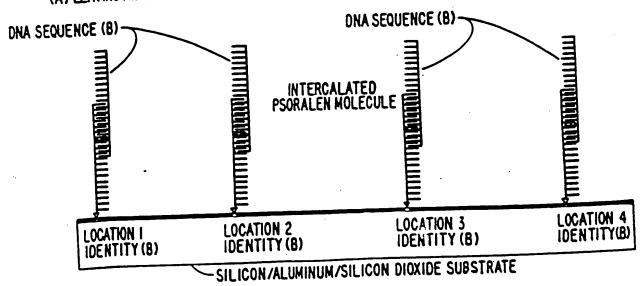


FIG. 10

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL

DNA SEQUENCE (B) FUNCTIONALIZED WITH A PSORALEN MOLECULE IS HYBRIDIZED TO SEQUENCE (A) LEAVING AN UNHYBRIDIZED OVERHANG SEQUENCE FOR SUBSEQUENT HYBRIDIZATION



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FIG. 11

LOCATION #1 IS MASKED FROM UV EXPOSURE WHILE LOCATIONS 2,3 &4 ARE EXPOSED ALLOWING THE PSORALEN MOLECULES TO COVALENTLY CROSS-LINK THE (A) AND (B) DNA SEQUENCE.

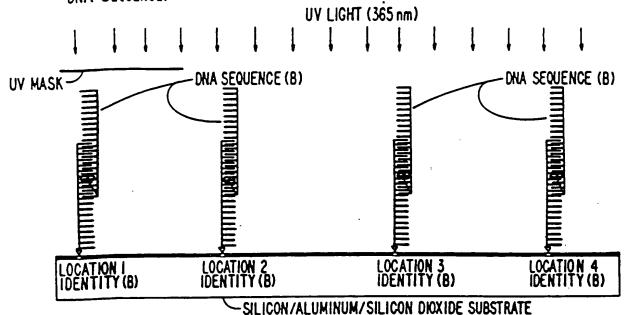
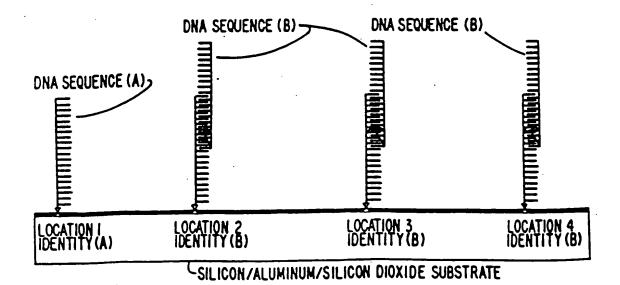


FIG. 12

PROCESS FOR PREPARING FOURID DNA WRITE MATERIAL

DEHYBRIDIZATION IS CARRIED OUT TO REMOVE THE NON-CROSSLINKED SEQUENCE (B) FROM THE IST LOCATION, WHICH NOW HAS A PERMANENT (A) SEQUENCE IDENTITY. DNA SEQUENCE (B) IS NOW COVALENTLY COUPLED TO LOCATIONS 2, 3 AND 4



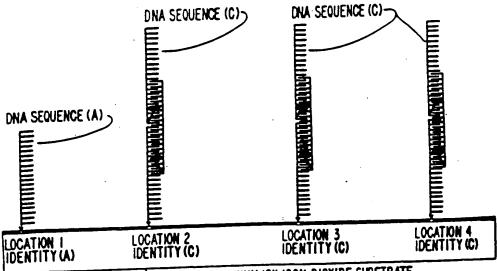
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FIG. 13.

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL

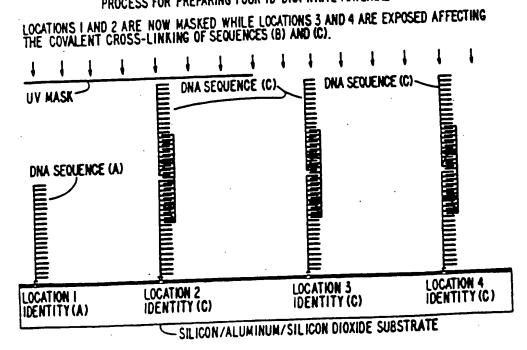
A PSORALEN FUCTIONALIZED DNA SEQUENCE (C) IS NOW HYBRIDIZED TO SEQUENCE (B), AND THE PROCESS IS REPEATED.



SILICON/ALUMINUM/SILICON DIOXIDE SUBSTRATE

FIG. 14.

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL



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FIG. 15

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL

DEHYBRIDIZATION IS CARRIED OUT TO REMOVE SEQUENCE (C) FROM LOCATION 2. A PERMANENT (B) DNA SEQUENCE IDENTITY IS NOW PRESENT AT LOCATION 2

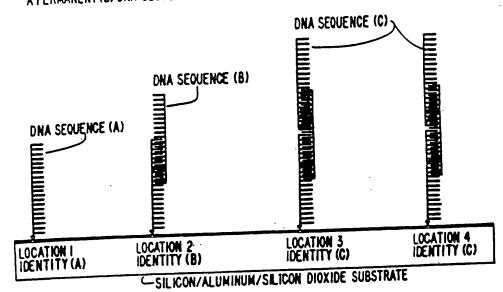
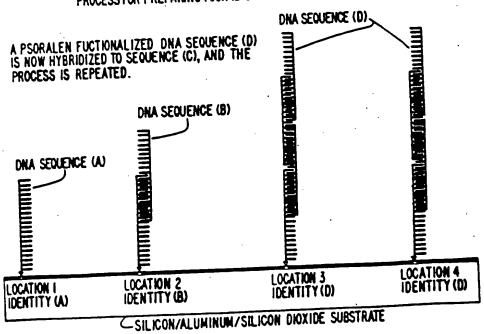


FIG. 16
PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL



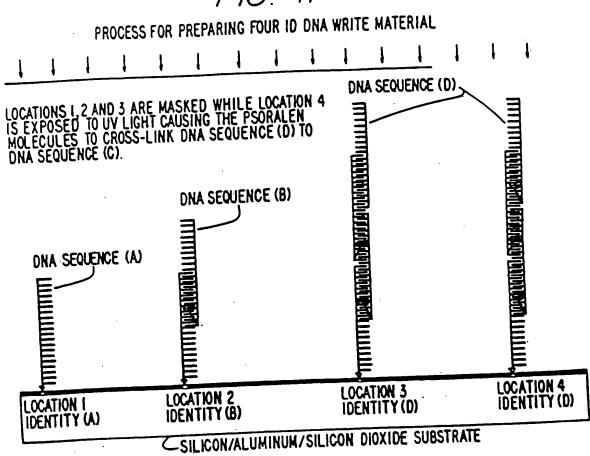
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FIG. 17



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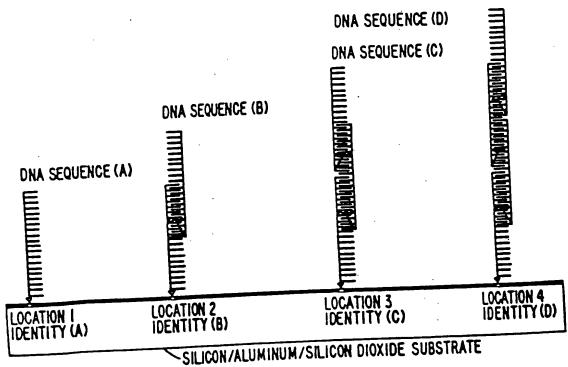
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FIG. 18

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL

DEHYBRIDIZATION IS CARRIED OUT TO REMOVE DNA SEQUENCE (D) FROM LOCATION 3. A PERMANENT (C) IDENTITY IS PRESENT AT LOCATION 3 AND A PERMANENT (D) IDENTITY IS PRESENT AT LOCATION 4. THIS COMPLETES THE PROCESS FOR PREPARING A FOUR ID DNA WRITE MATERIAL.



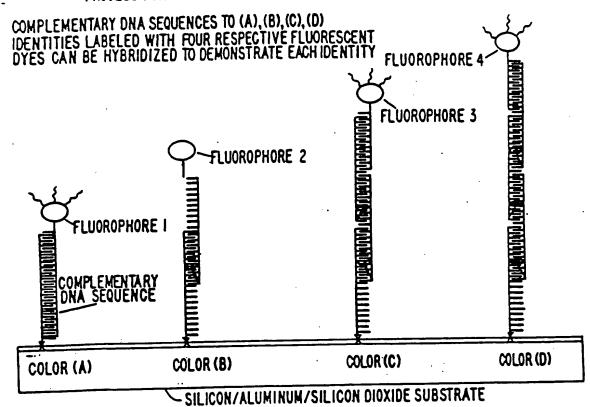
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FIG. 19

PROCESS FOR PREPARING FOUR ID DNA WRITE MATERIAL



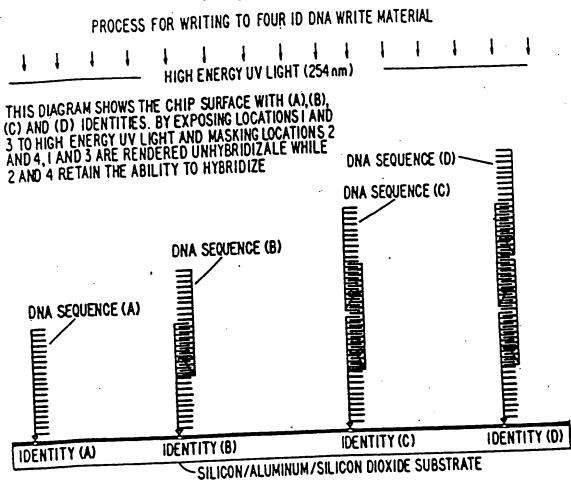
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FIG. 20



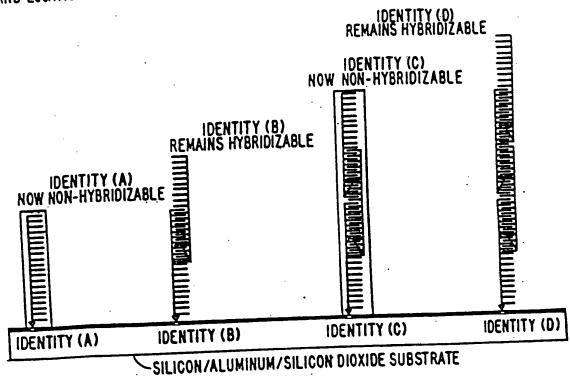
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FIG. 21

PROCESS FOR WRITING TO FOUR ID DNA WRITE MATERIAL

SELECTIVE UV EXPOSURE LEAVES LOCATIONS I AND 3 UNHYBRIDIZABLE AND LOCATIONS 2 AND 4 RETAIN THE ABILITY TO HYBRIDIZE

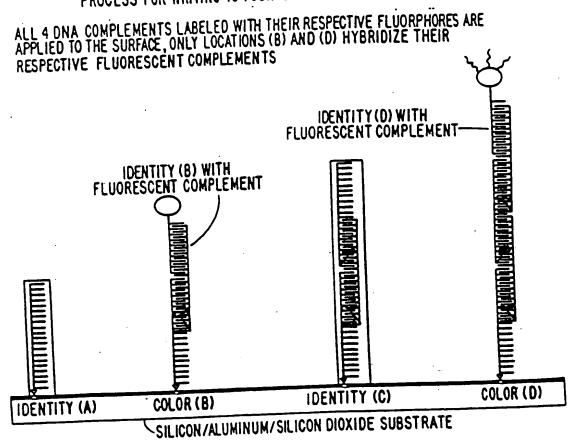


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FIG. 22.

PROCESS FOR WRITING TO FOUR ID DNA WRITE MATERIAL



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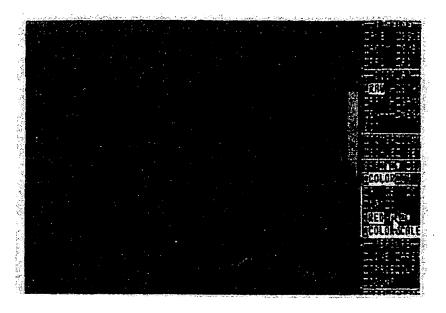


Fig. 23A

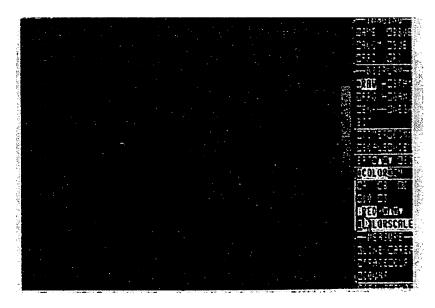


Fig. 23B

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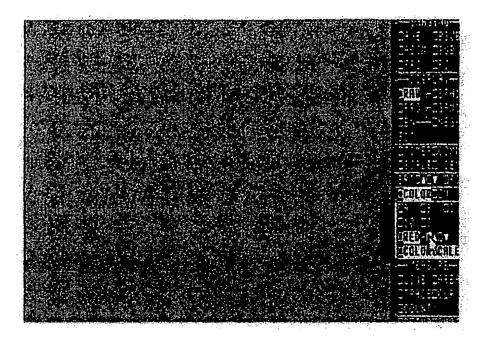


Fig. 24A

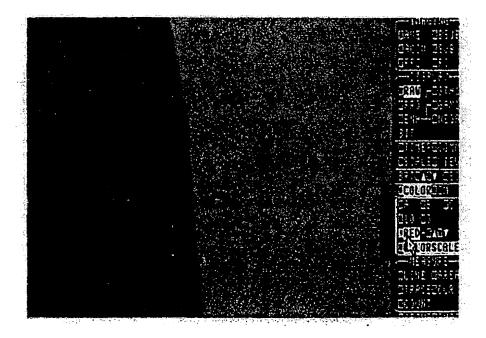


Fig. 24B

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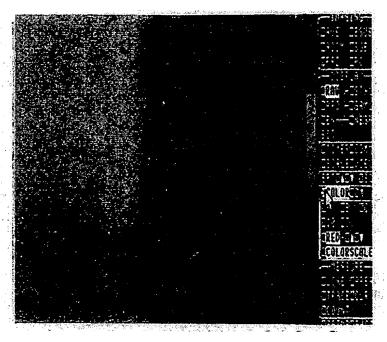


Fig. 25A

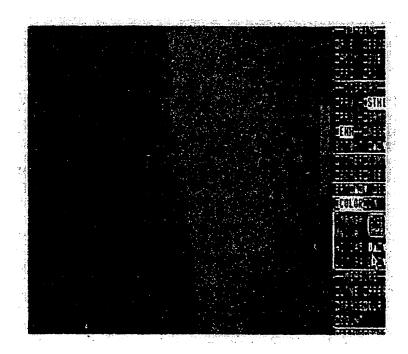


Fig. 25B

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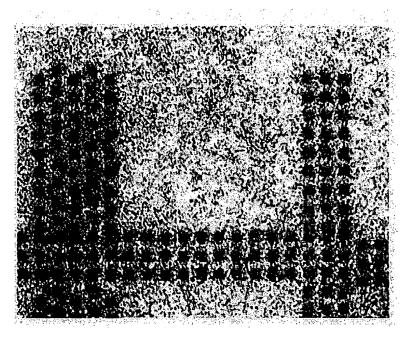


Fig. 26A

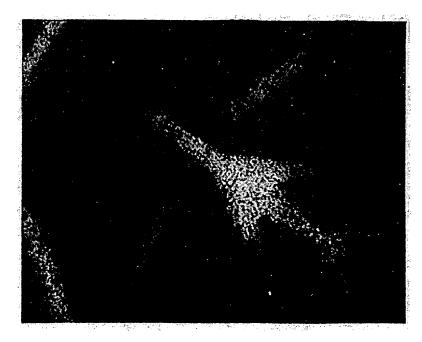


Fig. 26B

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and Electronic Applications

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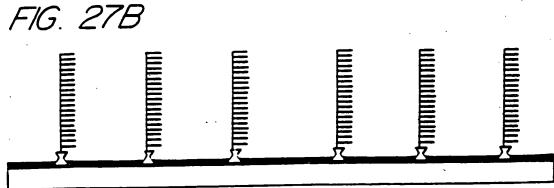
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FIG. 27A

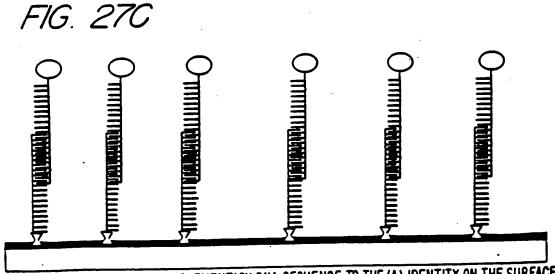
APS SUBSTRATE LAYER



CHIP SURFACE IS FUNCTIONALIZED ONLY WITH APS



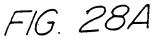
ORIGINAL CAPTURE DNA SEQUENCE A, WHICH IS NOT FLUORESCENTLY LABELED, IS COVALENTLY ATTACHED TO THE APS LAYER ON THE CHIP SURFACE

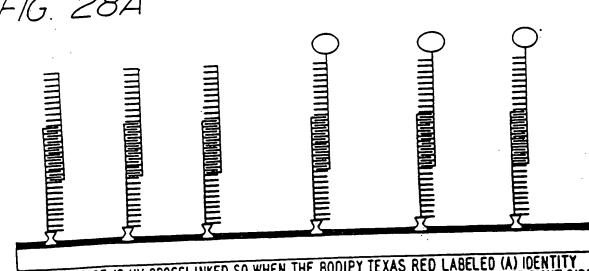


FLUORESCENTLY LABELED COMPLEMENTARY DNA SEQUENCE TO THE (A) IDENTITY ON THE SURFACE IS HYBRIDIZED TO THE ENTIRE CHIP LEAVING THE ENTIRE SURFACE BRIGHT

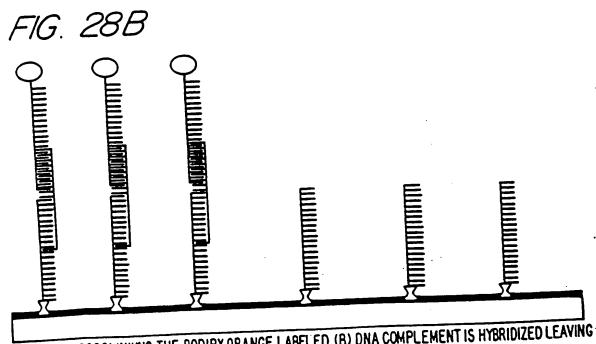
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1/2 OF SURFACE IS UV CROSSLINKED SO WHEN THE BODIPY TEXAS RED LABELED (A) IDENTITY COMPLEMENT IS HYBRIDIZED ACROSS THE ENTIRE CHIP ONLY THE NON-CROSSLINKED RIGHT SIDE OF THE CHIP ATTAINS COLOR

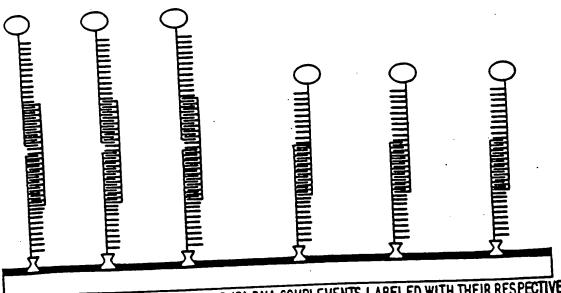


AFTER UV CROSSLINKING THE BODIPY ORANGE LABELED (B) DNA COMPLEMENT IS HYBRIDIZED LEAVING ONLY THE (B) IDENTITY LEFT SIDE OF THE CHIP BRIGHT

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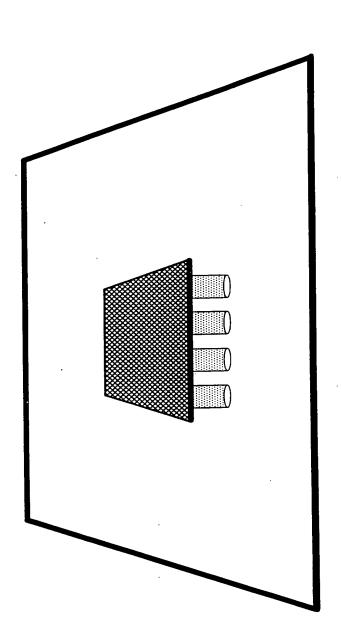
FIG. 28C



AFTER UV CROSSLINKING BOTH (A) AND (B) DNA COMPLEMENTS LABELED WITH THEIR RESPECTIVE FLUOROPHORES ARE HYBRIDIZED TO THE SURFACE, THE LEFT SIDE AT TAINING THE BODIPY ORANGE AND THE RIGHT ATTAINING THE BODIPY TEXAS RED COLOR

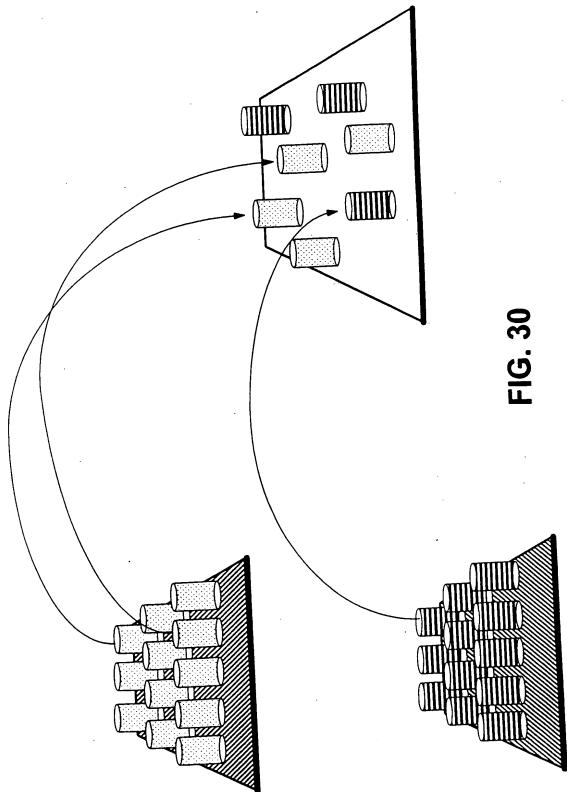
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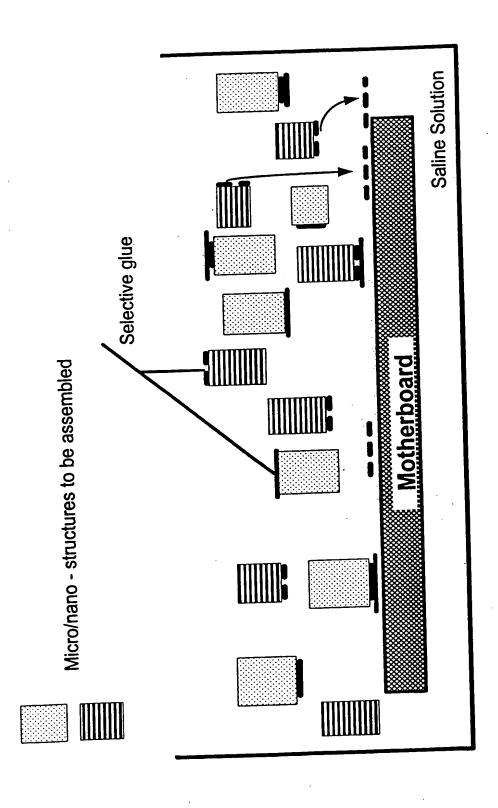
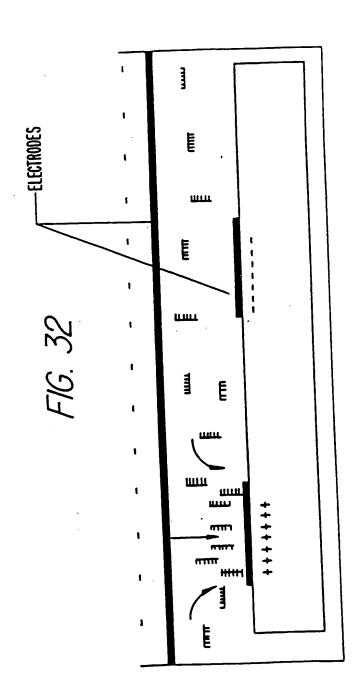


FIG. 31

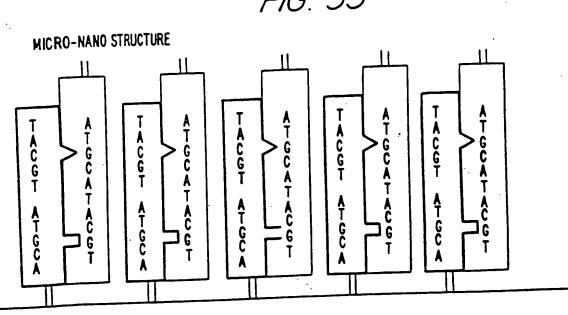
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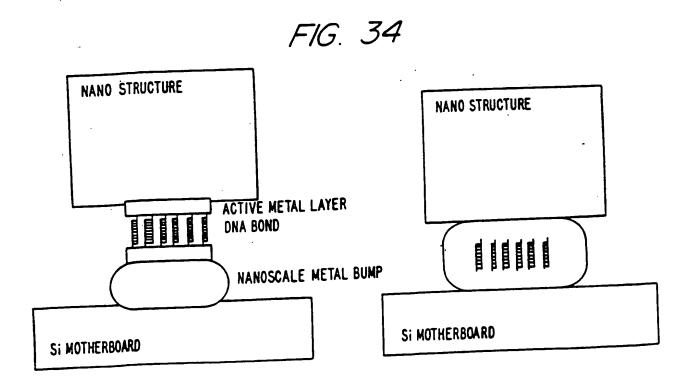
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FIG. 33



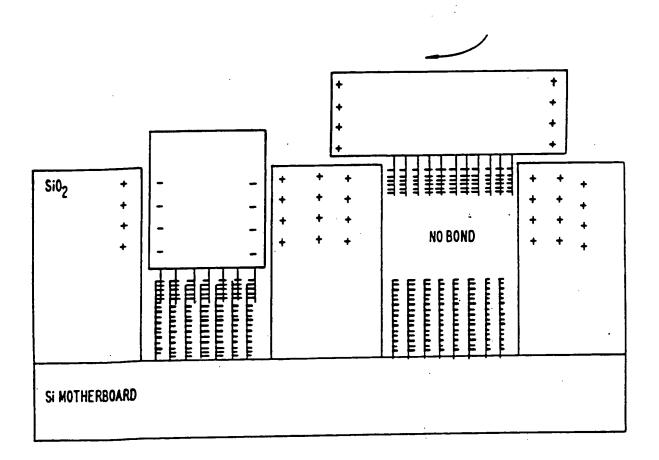
SILICON SUBSTRATE



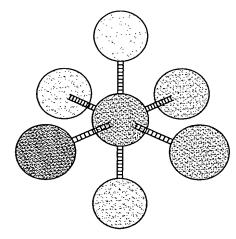
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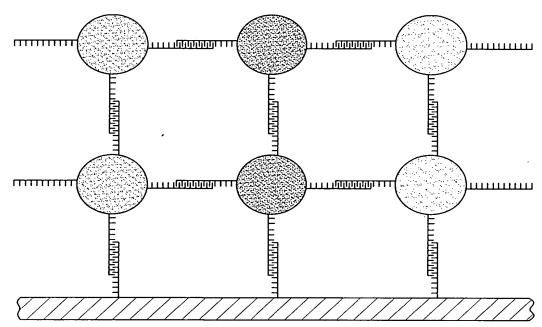
FIG. 35



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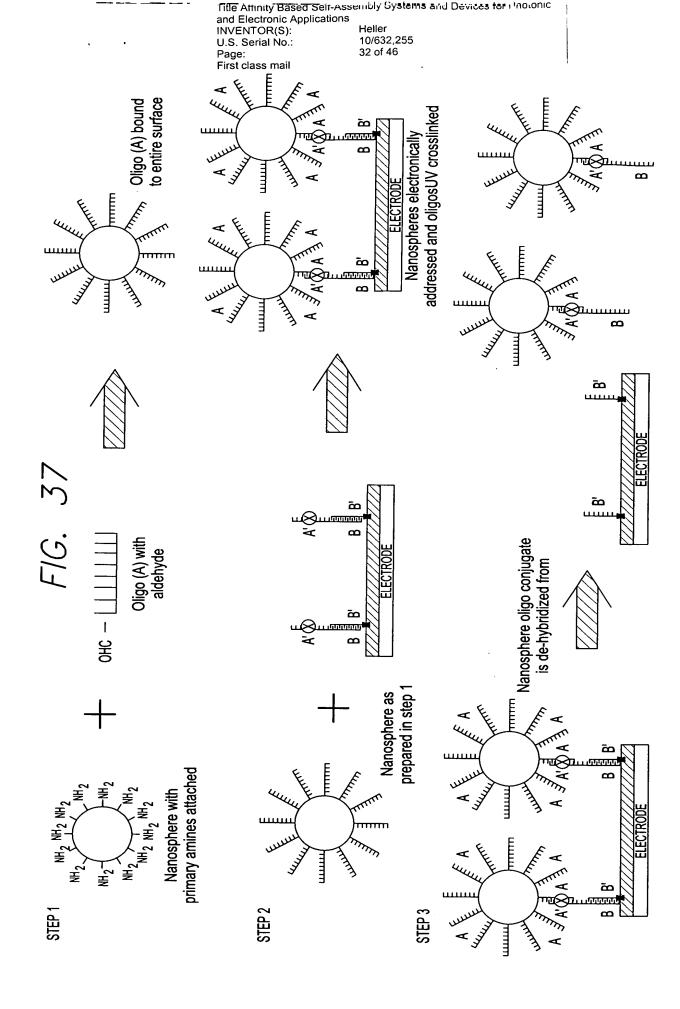


NANOSPHERES ARRANGED IN OCTAHEDRON USING 3D DNA NANOCONSTRUCTION TECHNIQUES



NANOSPHERES ARRANGED INTO LATTICE STRUCTURE AND BOUND TO SURFACE TO CREATE A 3D DEVICE

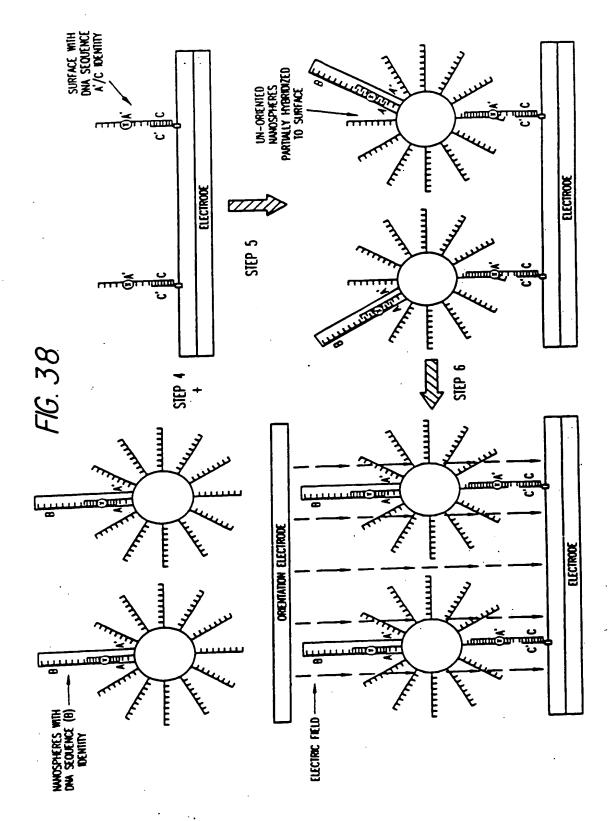
FIG. 36



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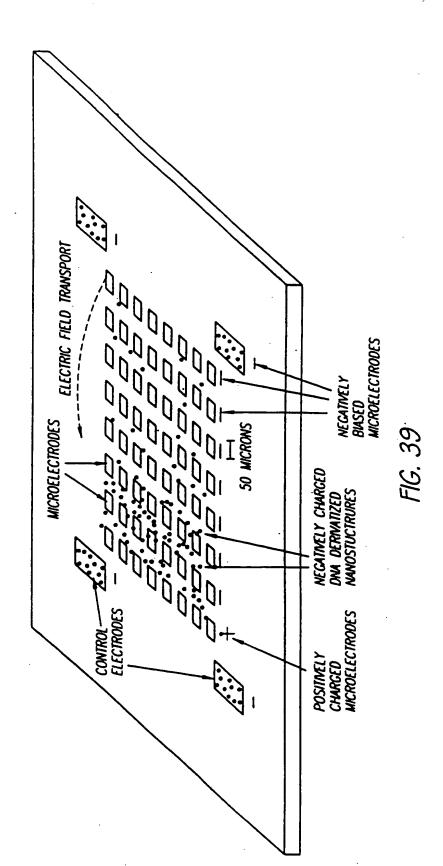
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Heller Heller 10/632,255 35 of 46 U.S. Serial No.: Page: First class mail DNA SEQUENCE HYBRIDIZE TO TYPE 1 NANOSTRUCTURES TYPE 2 NANOSTRUCTURES CONTAINING COMPLEMENTARY BOTH TYPE 1 AND TYPE 2 NANOSTRUCTURES. ARE NOW CLUSTERED ONTO THEIR RESPECTIVE MICROLOCATIONS TYPE 1 NANOSTRUCTURES ACCUMULATE AND HYBRIDIZE 10 THE SPECIFIC MICROLOCATION FIG. 40D 🚓 CHARGED TYPE 1 NANOSTRUCTURES 10 MOVE 10 CENTER LOCATION MICROLOCATION IS BIASED POSITIVE CAUSING THE NEGATIVELY NEGATIVELY CHARGED TYPE 2 NANOSTRUCTURES ARE ELECTRONICALLY ASSISTED SELF-ASSEMBLY BEGINS WHEN 0 MICROLOCATION | 1 IS BIASED NEGATIVE AND A CENTER INTRODUCED OVER THE ARRAY AND ACCUMULATE 0 0 ON THE POSITIVELY BIASED MICROLOCATIONS 0 TYPE 2 NANOSTRUCTURES ARE MOVED TO CENTER 0 LOCATION BY BIASING MICROLOCATION #8 NECATION POSITIVE TYPE 2 NANOSTRUCTURES FIG. 40C

TYPE 1 NANOSTRUCTURES ACCUMULATE ON THE POSITVELY BIASED MICRLOCATION

MOVE TOWARD POSITIVELY BIASED MICROLOCATION

- TYPE 1 NANOSTRUCTURES

NEGATIVELY CHARGED TYPE I NANOSTRUCTURES

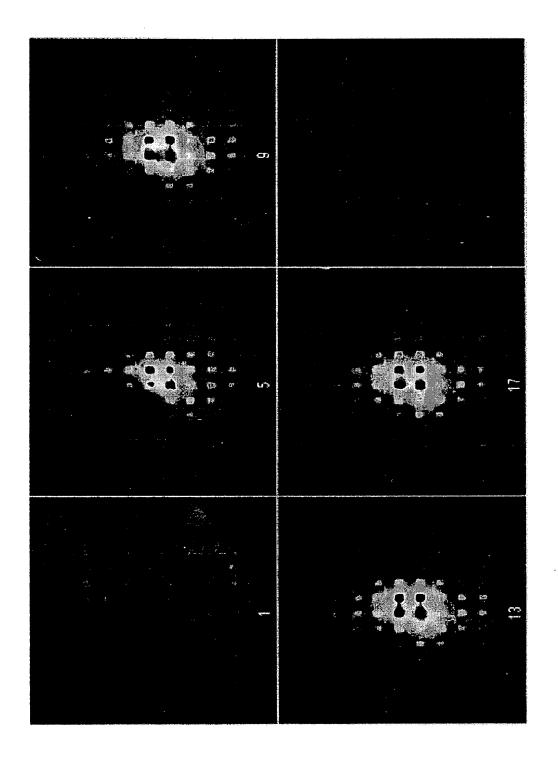
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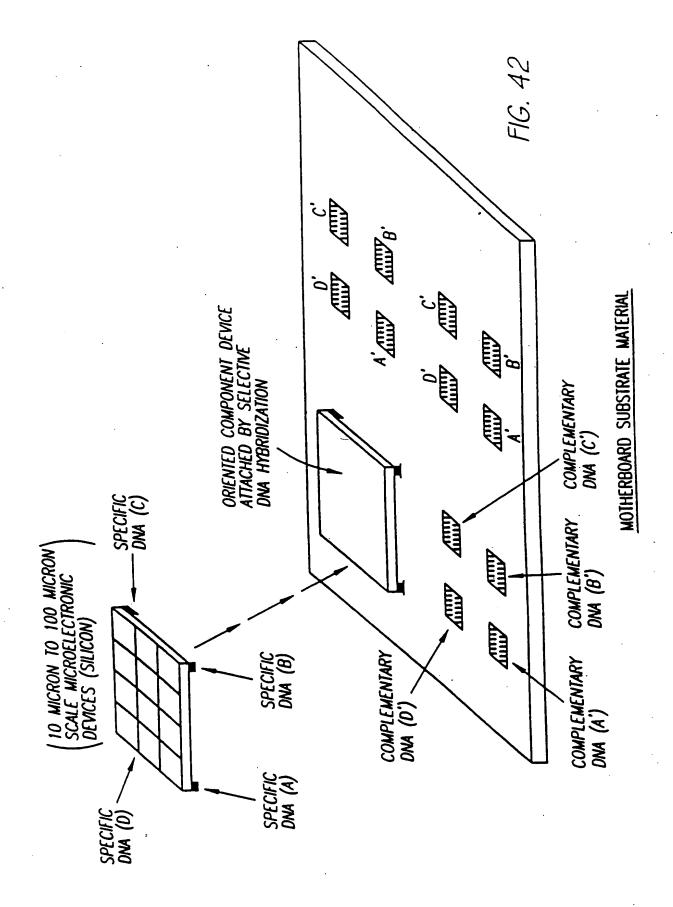
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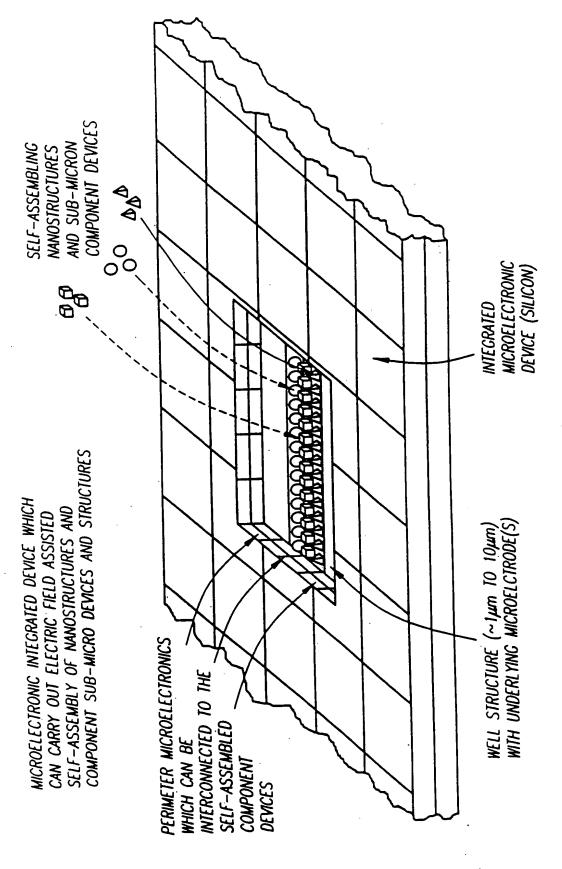
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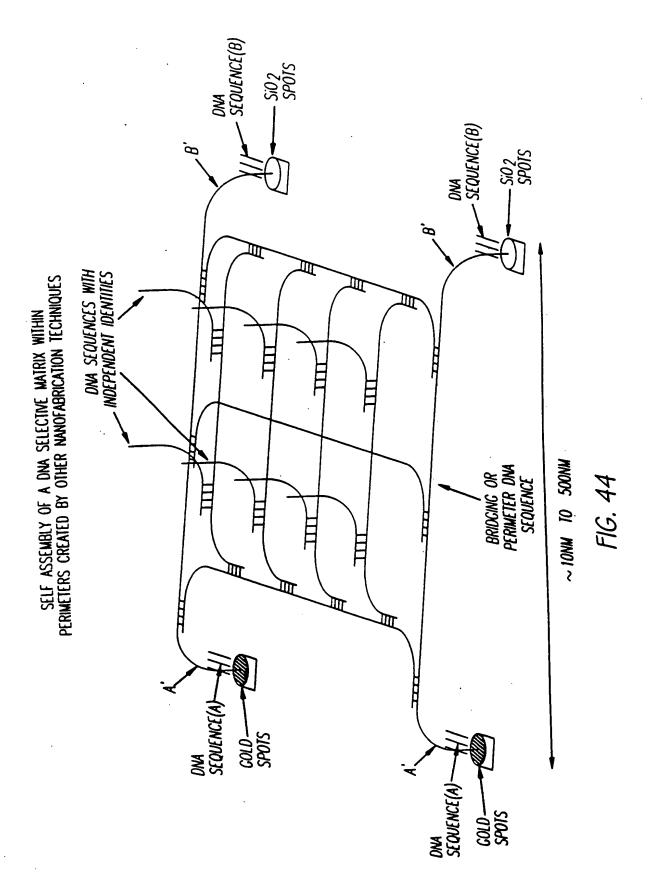
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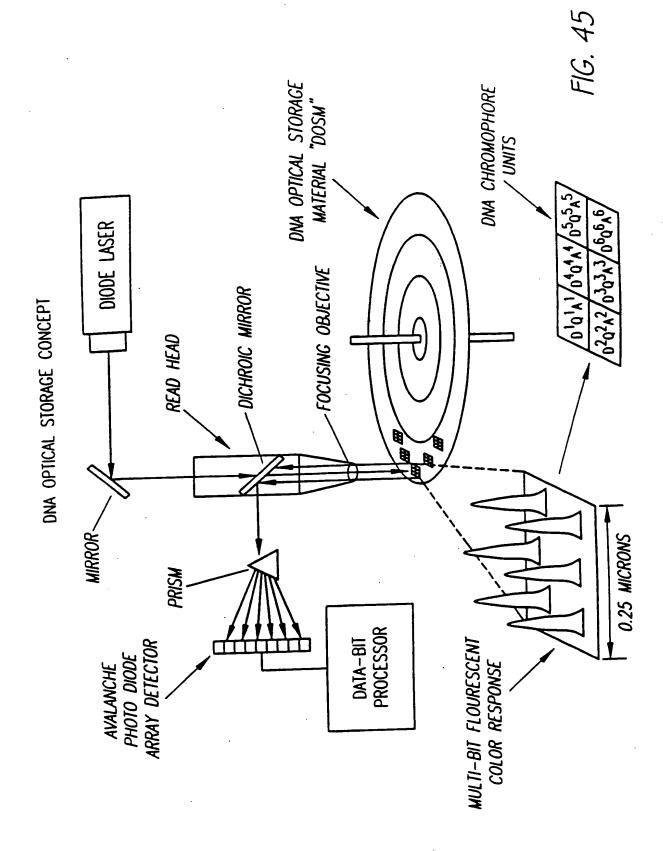
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and Electronic Applications
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Title Affinity Based Self-Assembly Systems and Devices for Photonic and Electronic Applications Heller 10/632,255 40 of 46 INVENTOR(S): U.S. Serial No.:

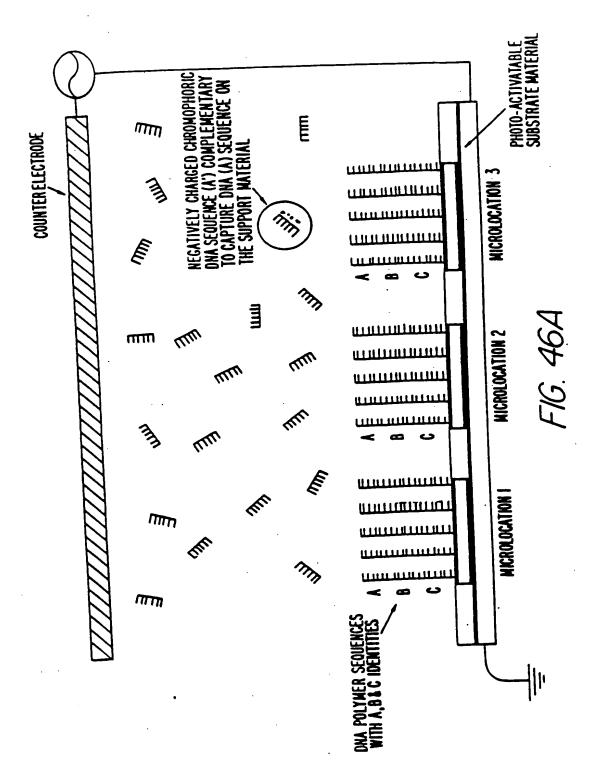


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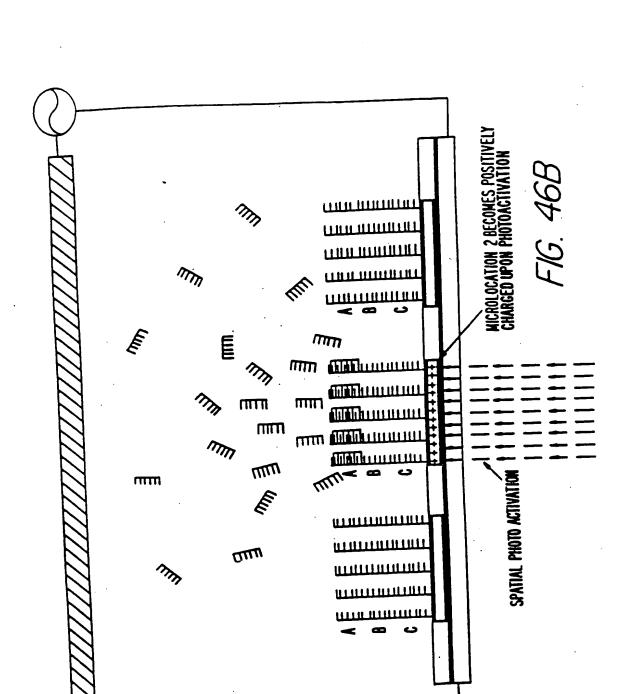
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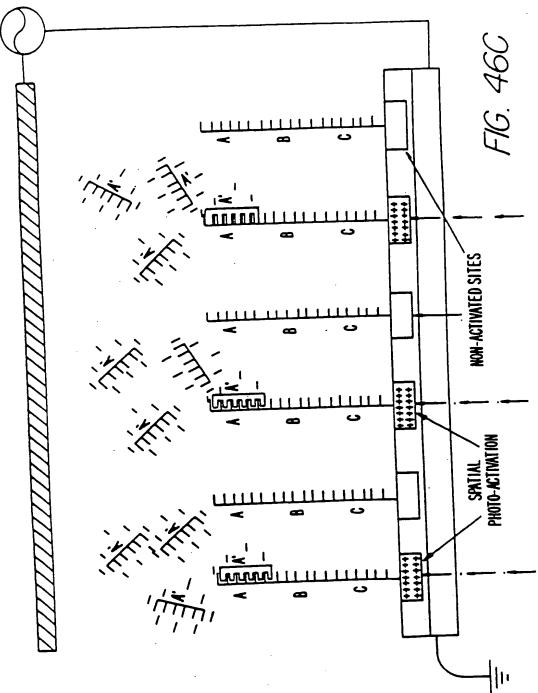
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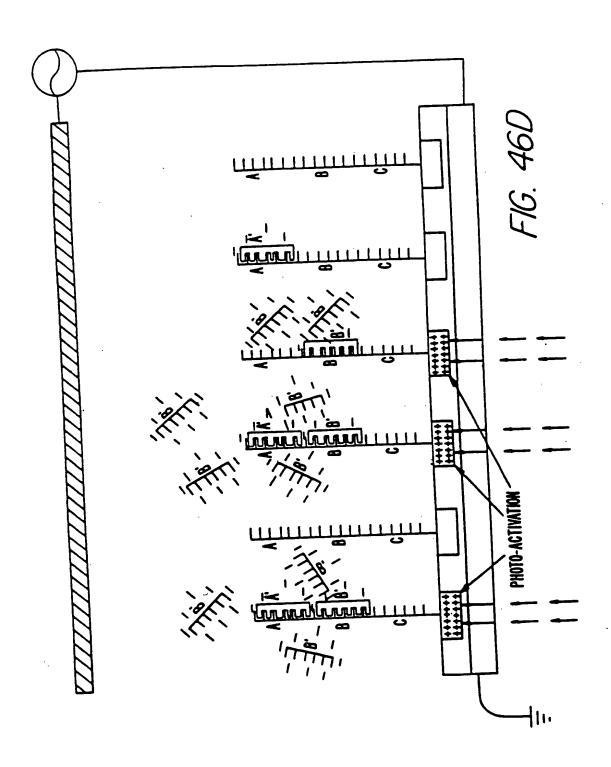


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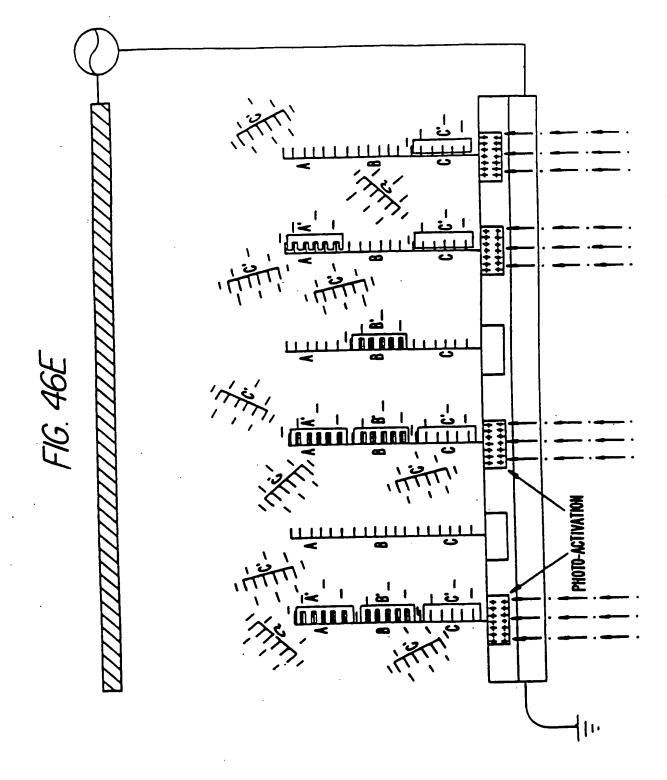




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